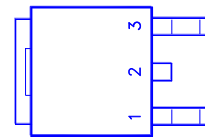
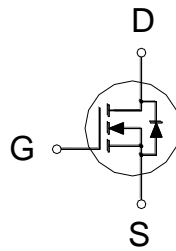




**PRODUCT SUMMARY**

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
100V	10.5m $\Omega$	59A



1. GATE
2. DRAIN
3. SOURCE

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 ° C Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	100	V
Gate-Source Voltage		$V_{GS}$	±20	V
Continuous Drain Current <sup>2</sup>	T <sub>C</sub> = 25 ° C	$I_D$	59	A
	T <sub>C</sub> = 100 ° C		37	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	150	
Avalanche Current		$I_{AS}$	TBD	
Avalanche Energy	L = 1mH	$E_{AS}$	TBD	mJ
Power Dissipation	T <sub>C</sub> = 25 ° C	$P_D$	83	W
	T <sub>C</sub> = 100 ° C		33	
Operating Junction & Storage Temperature Range		T <sub>j</sub> , T <sub>stg</sub>	-55 to 150	° C

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.5	° C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>Package limitation current is 55A

**ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25 ° C, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.4	2	3	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$			±100	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 100V, V_{GS} = 0V$			1	$\mu A$
		$V_{DS} = 100V, V_{GS} = 0V, T_J = 125\text{ ° C}$			100	

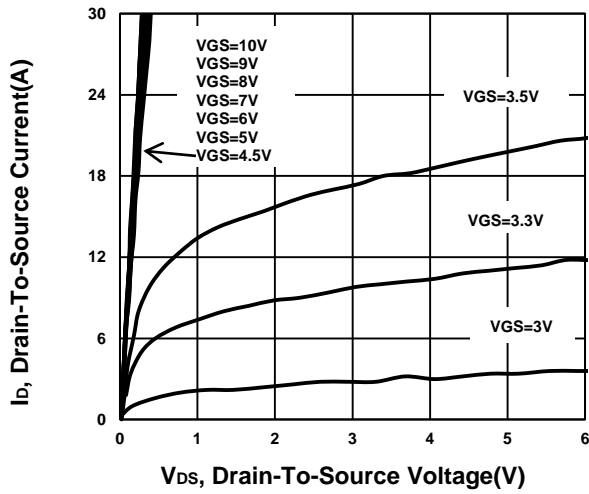
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 10A$	11	15	mΩ
		$V_{GS} = 10V, I_D = 12A$	8	10.5	
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 12A$	60		S
<b>DYNAMIC</b>					
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 50V, f = 1MHz$	2167		pF
Output Capacitance	$C_{oss}$		194		
Reverse Transfer Capacitance	$C_{rss}$		13		
Gate Resistance	$R_g$	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$	1.5		Ω
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{DS} = 50V, I_D = 12A$	$V_{GS} = 10V$	40	nC
			$V_{GS} = 4.5V$	23	
Gate-Source Charge <sup>2</sup>	$Q_{gs}$		6.6		
Gate-Drain Charge <sup>2</sup>	$Q_{gd}$		12		
Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$		13	nS	
Rise Time <sup>2</sup>	$t_r$		34		
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$	50			
Fall Time <sup>2</sup>	$t_f$	61			
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T<sub>J</sub> = 25 °C)</b>					
Continuous Current <sup>3</sup>	$I_S$			59	A
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = 12A, V_{GS} = 0V$		1.2	V
Reverse Recovery Time	$t_{rr}$	$I_F = 12A, di_F/dt = 100A/\mu s$		36	nS
Reverse Recovery Charge	$Q_{rr}$			50	nC

<sup>1</sup>Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

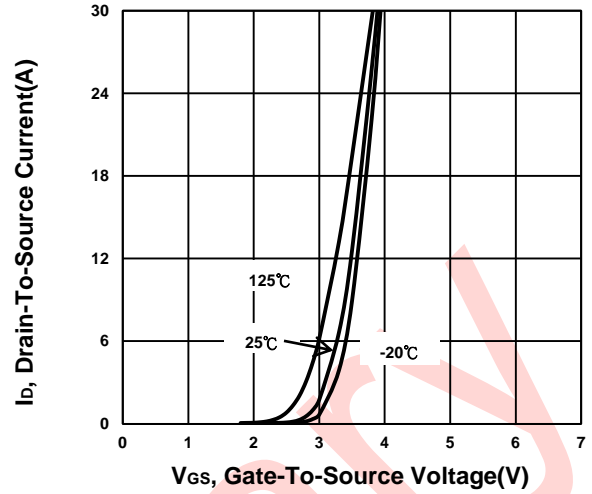
<sup>2</sup>Independent of operating temperature.

<sup>3</sup>Package limitation current is 55A

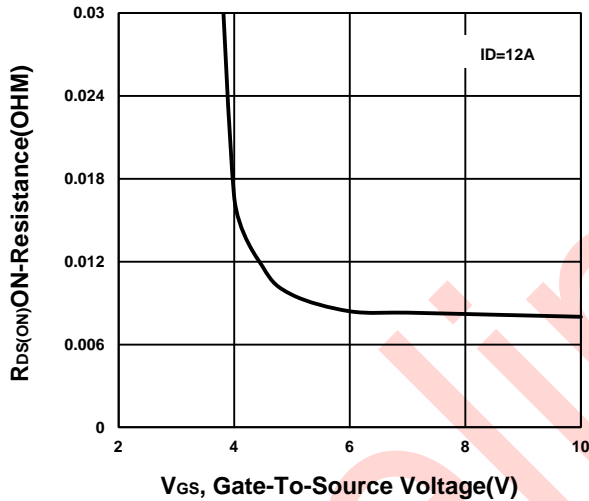
**Output Characteristics**



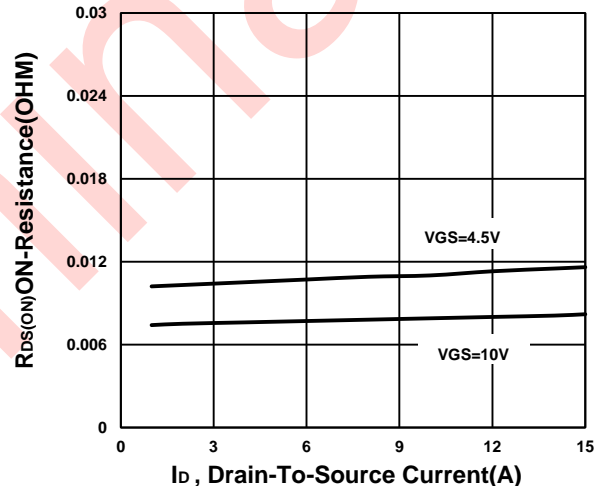
**Transfer Characteristics**



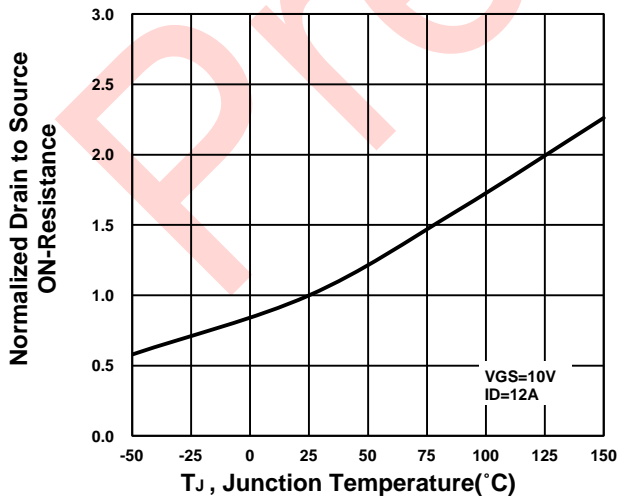
**On-Resistance VS Gate-To-Source Voltage**



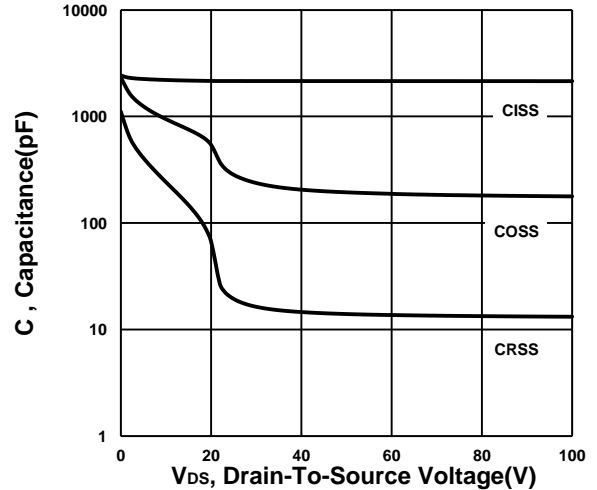
**On-Resistance VS Drain Current**



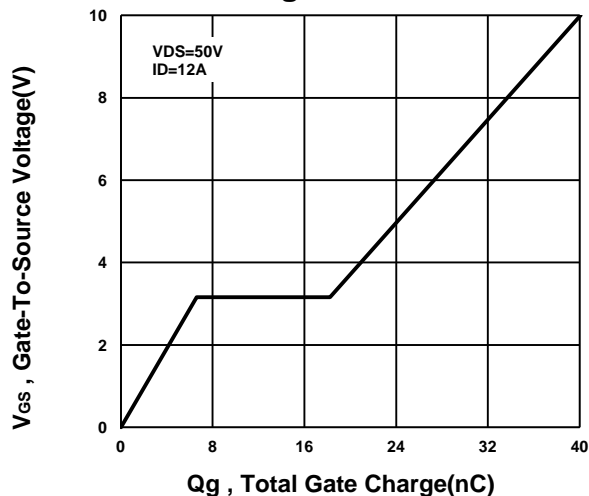
**On-Resistance VS Temperature**



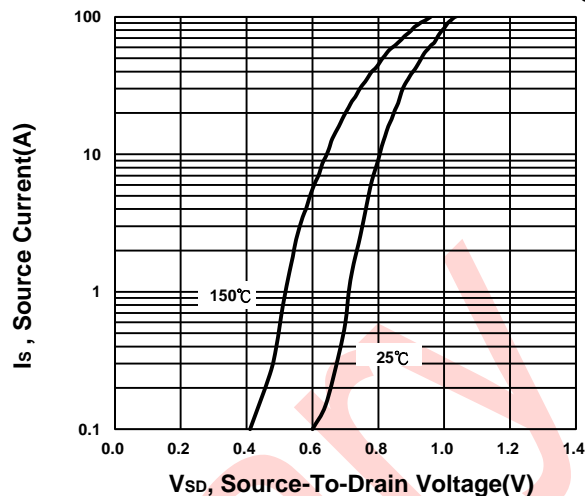
**Capacitance Characteristic**



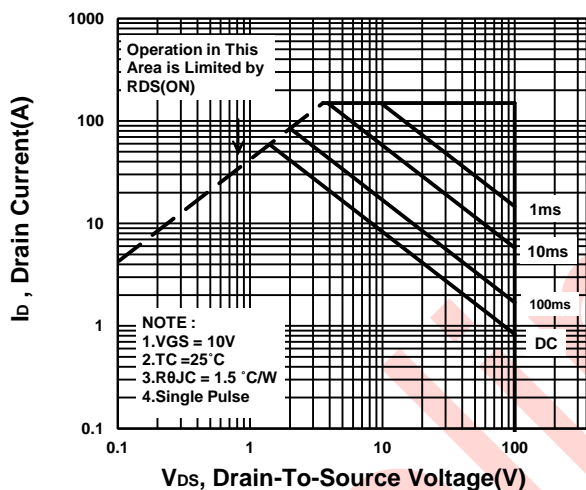
**Gate charge Characteristics**



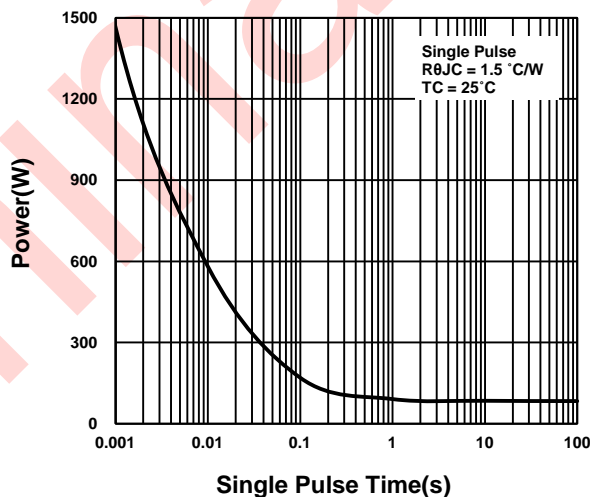
**Source-Drain Diode Forward Voltage**



**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**

